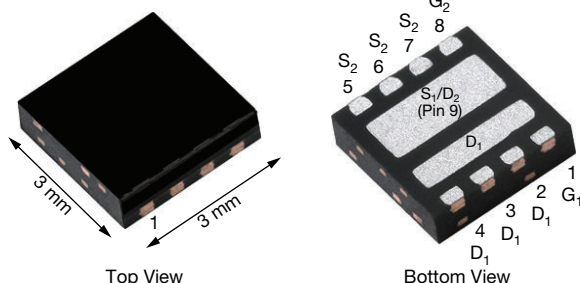


# Dual N-Channel 30 V (D-S) MOSFET

## PRODUCT SUMMARY

	V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) MAX.	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)
Channel-1 and Channel-2	30	0.0115 at V <sub>GS</sub> = 10 V	30 <sup>a</sup>	4.5 nC
		0.0153 at V <sub>GS</sub> = 4.5 V	27.5	

**PowerPAIR® 3 x 3**


## Ordering Information:

SiZ342DT-T1-GE3 (lead (Pb)-free and halogen-free)

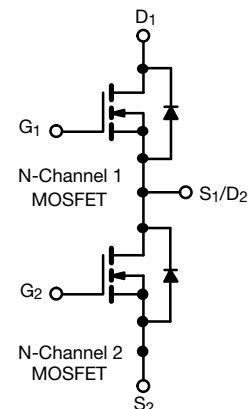
## FEATURES

- PowerPAIR® optimizes high-side and low-side MOSFETs for synchronous buck converters
- TrenchFET® Gen IV power MOSFETs
- 100 % R<sub>g</sub> and UIS tested
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## APPLICATIONS

- Synchronous buck
  - Battery charging
  - Computer system power
  - Graphic cards
- POL



## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)

PARAMETER	CHANNEL-1 AND CHANNEL-2		
	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	+20 / -16	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	I <sub>D</sub>	30 <sup>a</sup>	A
		26.5	
		15.6 <sup>b, c</sup>	
		12.4 <sup>b, c</sup>	
Pulsed Drain Current (t = 100 μs)	I <sub>DM</sub>	100	A
Continuous Source Drain Diode Current	I <sub>S</sub>	13.9	
		3.1 <sup>b, c</sup>	
Avalanche Current	I <sub>AS</sub>	10	
Single Pulse Avalanche Energy	E <sub>AS</sub>	5	mJ
Maximum Power Dissipation	P <sub>D</sub>	16.7	W
		10.7	
		3.7 <sup>b, c</sup>	
		2.4 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C
Soldering Recommendations (Peak Temperature) <sup>d, e</sup>		260	

## Notes

- Package limited.
- Surface mounted on 1" x 1" FR4 board.
- t = 10 s.
- See solder profile ([www.vishay.com/doc?73257](http://www.vishay.com/doc?73257)). The PowerPAIR 3 x 3 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

**THERMAL RESISTANCE RATINGS**

PARAMETER		CHANNEL-1 AND CHANNEL-2			
		SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient <sup>a, b</sup>	$t \leq 10$ s	$R_{thJA}$	27	34	°C/W
Maximum Junction-to-Case (Drain)	Steady State	$R_{thJC}$	6	7.5	

**Notes**

a. Surface mounted on 1" x 1" FR4 board.

b. Maximum under steady state conditions is 69 °C/W.

**SPECIFICATIONS** ( $T_J = 25$  °C, unless otherwise noted)

PARAMETER	CHANNEL-1 AND CHANNEL-2					
	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0$ V, $I_D = 250$ $\mu$ A	30	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250$ $\mu$ A	-	20	-	mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250$ $\mu$ A	-	-5.6	-	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250$ $\mu$ A	1.2	-	2.4	V
Gate Source Leakage	$I_{GSS}$	$V_{DS} = 0$ V, $V_{GS} = +20$ V/ -16 V	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 30$ V, $V_{GS} = 0$ V	-	-	1	$\mu$ A
		$V_{DS} = 30$ V, $V_{GS} = 0$ V, $T_J = 55$ °C	-	-	5	
On-State Drain Current <sup>b</sup>	$I_{D(on)}$	$V_{DS} \leq 5$ V, $V_{GS} = 10$ V	10	-	-	A
Drain-Source On-State Resistance <sup>b</sup>	$R_{DS(on)}$	$V_{GS} = 10$ V, $I_D = 14.4$ A	-	0.0084	0.0115	$\Omega$
		$V_{GS} = 4.5$ V, $I_D = 13$ A	-	0.0111	0.0153	
Forward Transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15$ V, $I_D = 14.4$ A	-	37	-	S
<b>Dynamic <sup>a</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 15$ V, $V_{GS} = 0$ V, $f = 1$ MHz	-	650	-	pF
Output Capacitance	$C_{oss}$		-	236	-	
Reverse Transfer Capacitance	$C_{rss}$		-	20	-	
$C_{rss} / C_{iss}$ Ratio			0.03	-	0.06	-
Total Gate Charge	$Q_g$	$V_{DS} = 15$ V, $V_{GS} = 10$ V, $I_D = 14.4$ A	-	10	20	nC
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15$ V, $V_{GS} = 4.5$ V, $I_D = 14.4$ A	-	4.5	9	
Gate-Drain Charge	$Q_{gd}$		-	2.1	-	
Output Charge	$Q_{oss}$		-	0.7	-	
			-	6.6	-	
Gate Resistance	$R_g$	$f = 1$ MHz	0.3	1.4	2.8	$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15$ V, $R_L = 1.5$ $\Omega$ $I_D \equiv 10$ A, $V_{GEN} = 4.5$ V, $R_g = 1$ $\Omega$	-	15	23	ns
Rise Time	$t_r$		-	50	75	
Turn-Off Delay Time	$t_{d(off)}$		-	16	24	
Fall Time	$t_f$		-	10	20	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15$ V, $R_L = 1.5$ $\Omega$ $I_D \equiv 10$ A, $V_{GEN} = 10$ V, $R_g = 1$ $\Omega$	-	8	16	
Rise Time	$t_r$		-	15	23	
Turn-Off Delay Time	$t_{d(off)}$		-	17	26	
Fall Time	$t_f$		-	7	14	

**SPECIFICATIONS** ( $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

PARAMETER	CHANNEL-1 AND CHANNEL-2					
	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25\text{ }^{\circ}\text{C}$	-	-	13.9	A
Pulse Diode Forward Current ( $t = 100\text{ }\mu\text{s}$ )	$I_{SM}$		-	-	100	
Body Diode Voltage	$V_{SD}$	$I_S = 10\text{ A}$ , $V_{GS} = 0\text{ V}$	-	0.8	1.2	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 10\text{ A}$ , $dI/dt = 100\text{ A}/\mu\text{s}$ , $T_J = 25\text{ }^{\circ}\text{C}$	-	20	35	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	10	20	nC
Reverse Recovery Fall Time	$t_a$		-	12.5	-	ns
Reverse Recovery Rise Time	$t_b$		-	7.5	-	

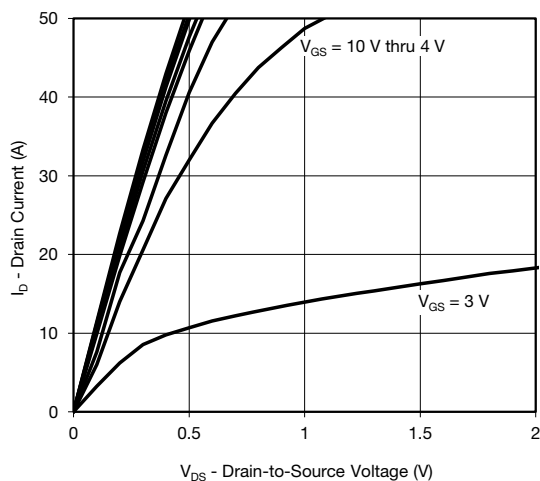
**Notes**

- Guaranteed by design, not subject to production testing.
- Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

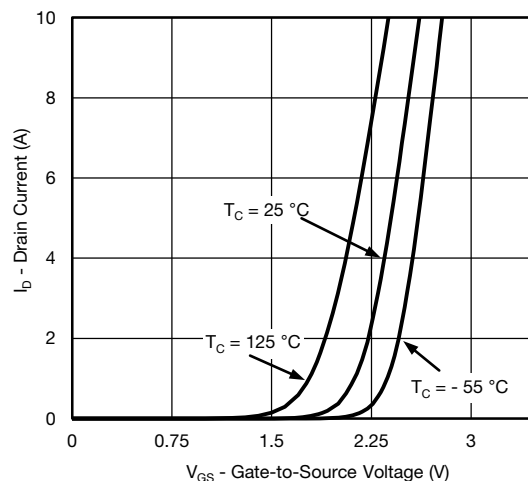
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



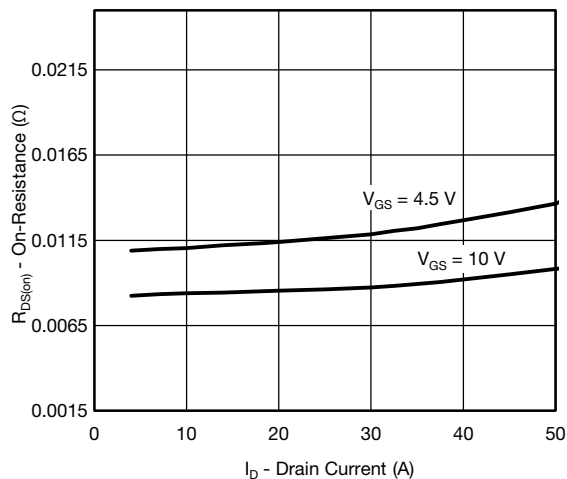
**CHANNEL-1 AND CHANNEL-2 TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



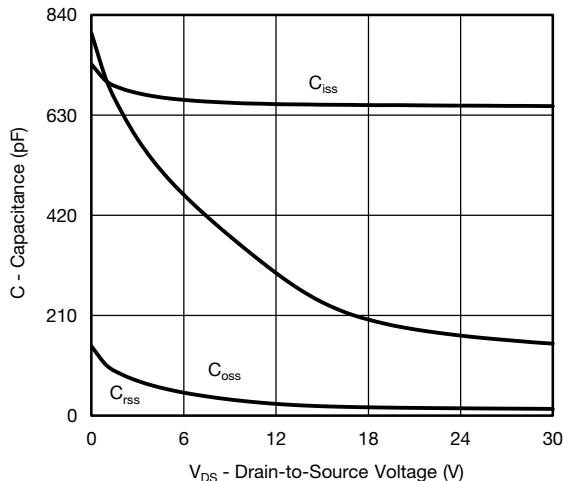
**Output Characteristics**



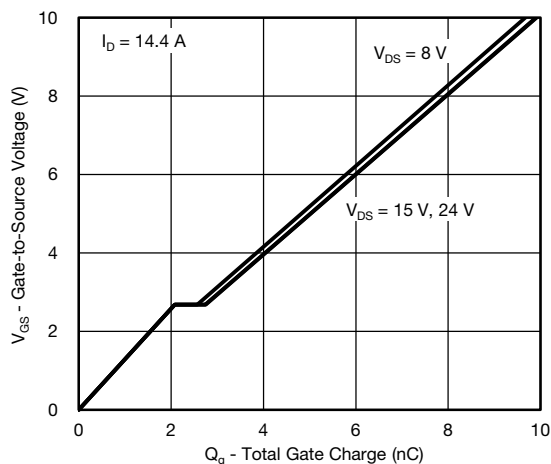
**Transfer Characteristics**



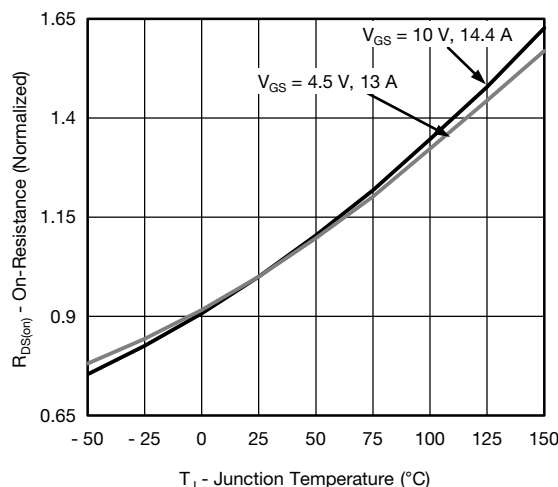
**On-Resistance vs. Drain Current**



**Capacitance**



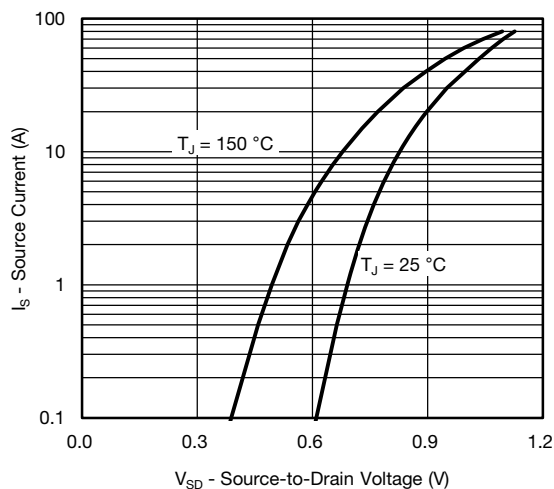
**Gate Charge**



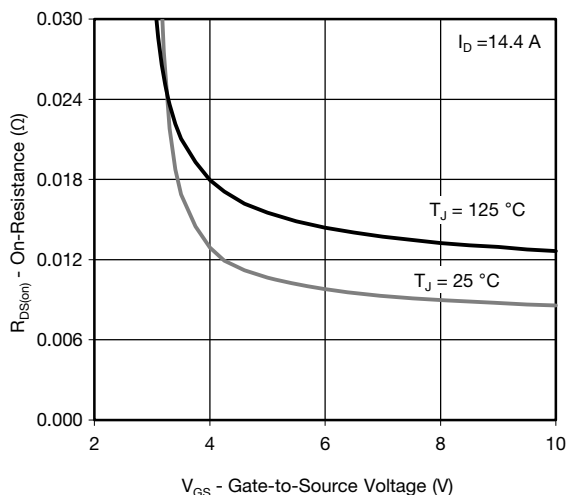
**On-Resistance vs. Junction Temperature**



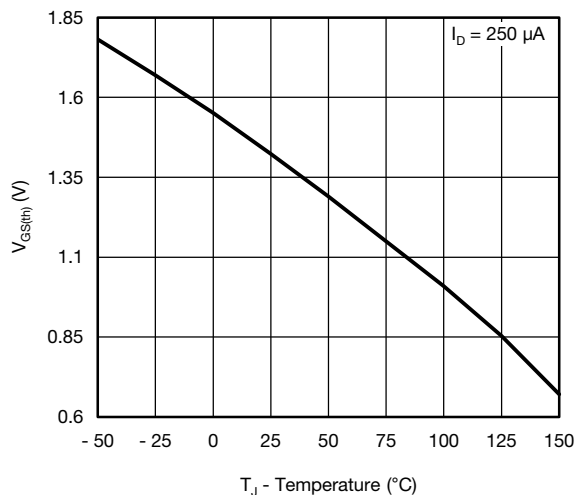
**CHANNEL-1 AND CHANNEL-2 TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



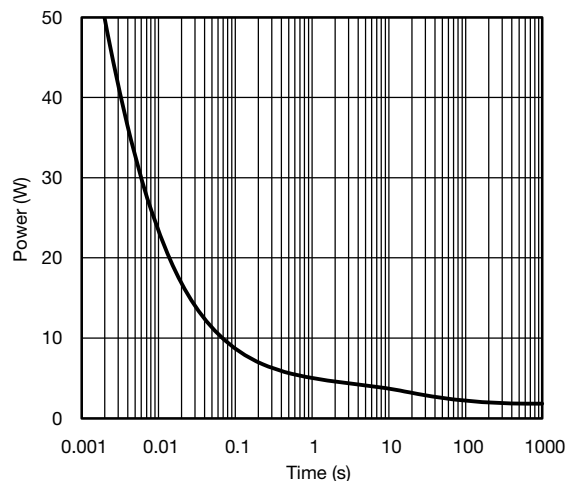
**Source-Drain Diode Forward Voltage**



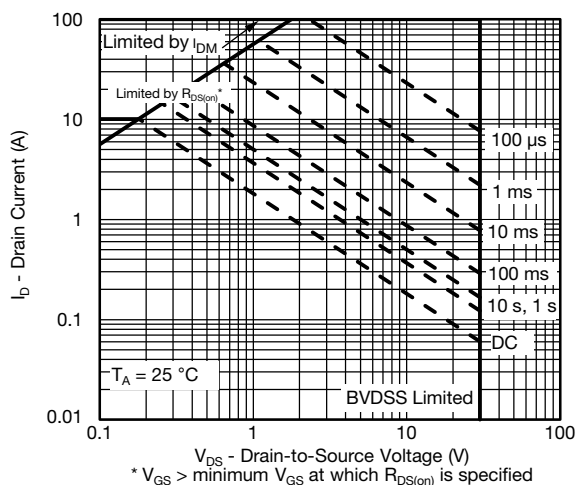
**On-Resistance vs. Gate-to-Source Voltage**



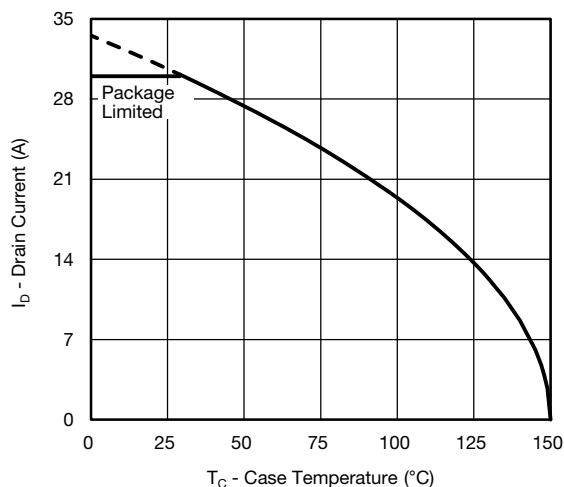
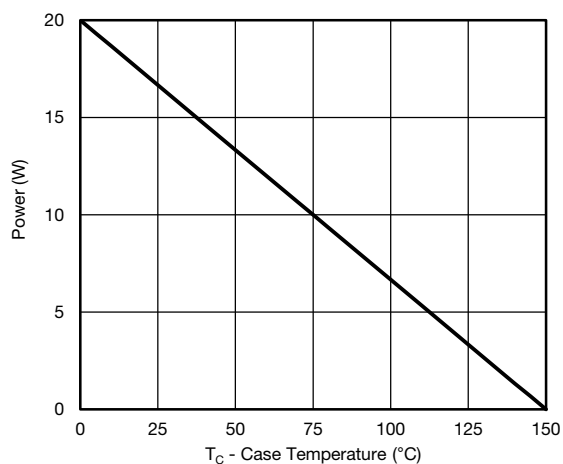
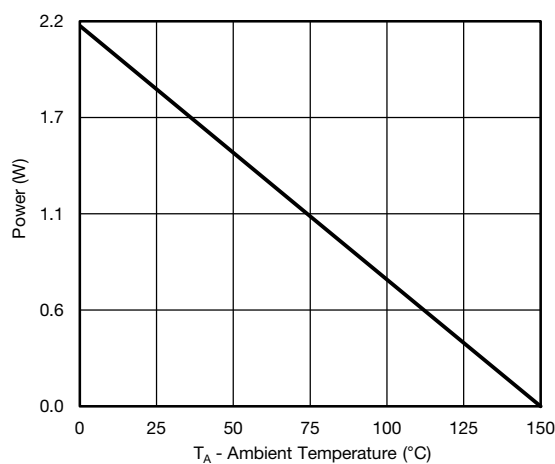
**Threshold Voltage**



**Single Pulse Power (Junction-to-Ambient)**



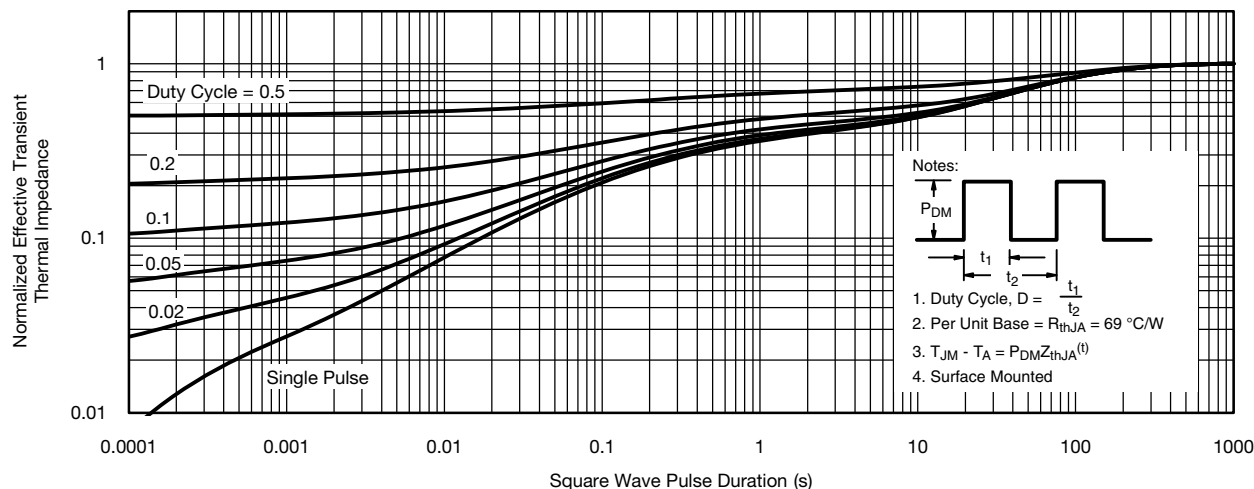
**Safe Operating Area, Junction-to-Ambient**

**CHANNEL-1 AND CHANNEL-2 TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Current Derating\***

**Power, Junction-to-Case**

**Power, Junction-to-Ambient**

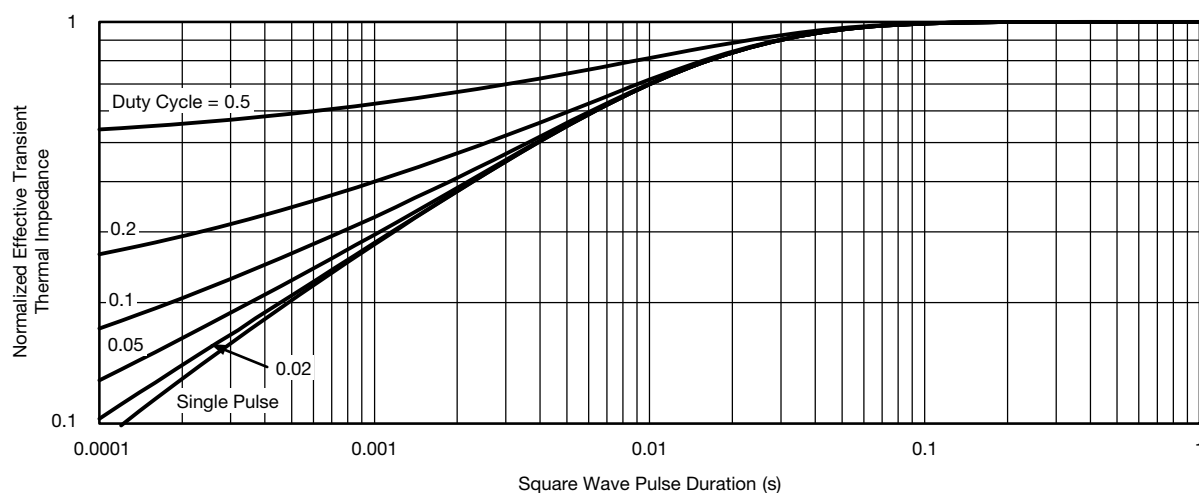
\* The power dissipation  $P_D$  is based on  $T_{J(max.)} = 150\text{ °C}$ , using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



**CHANNEL-1 AND CHANNEL-2 TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Ambient**

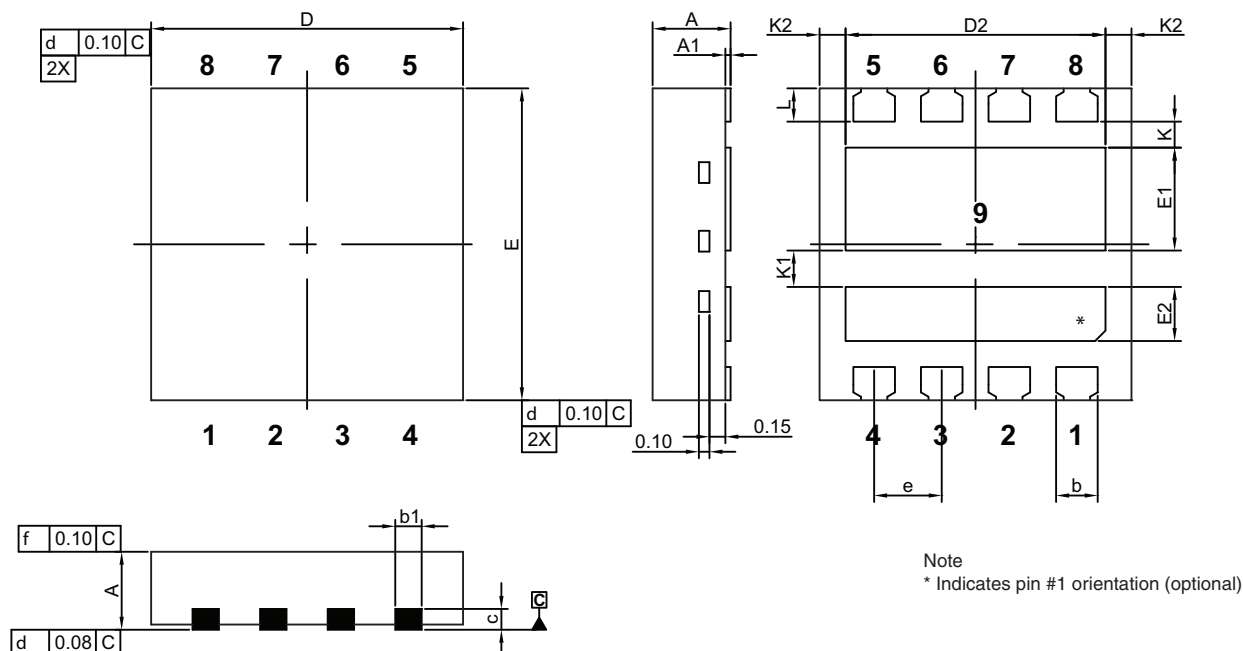


**Normalized Thermal Transient Impedance, Junction-to-Case**

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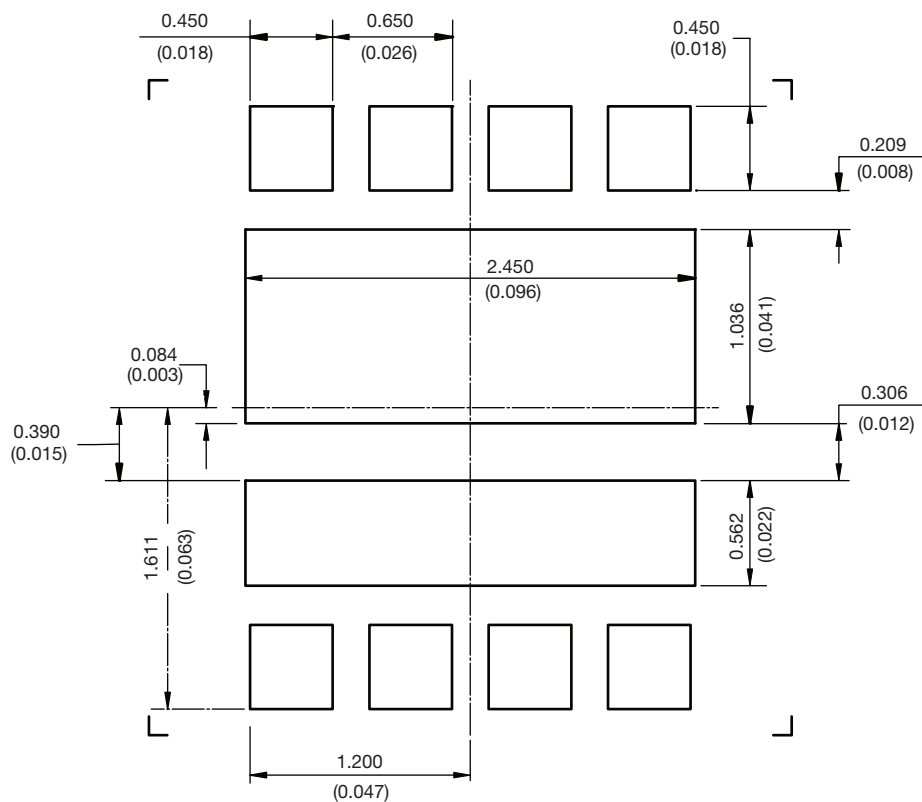
## PowerPAIR® 3 x 3 Case Outline



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00		0.05	0.000		0.002
b	0.35	0.40	0.45	0.014	0.016	0.018
b1	0.20	0.25	0.38	0.008	0.010	0.015
C	0.18	0.20	0.23	0.007	0.008	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
D2	2.35	2.40	2.45	0.093	0.094	0.096
E	2.90	3.00	3.10	0.114	0.118	0.122
E1	0.94	0.99	1.04	0.037	0.039	0.041
E2	0.47	0.52	0.57	0.019	0.020	0.022
e	0.65 BSC			0.026 BSC		
K	0.25 typ.			0.010 typ.		
K1	0.35 typ.			0.014 typ.		
K2	0.30 typ.			0.012 typ.		
L	0.27	0.32	0.37	0.011	0.013	0.015
ECN: T12-0347-Rev. C, 18-Jun-12						
DWG: 5998						



### RECOMMENDED MINIMUM PAD FOR PowerPAIR® 3 x 3



Recommended PAD for PowerPAIR 3 x 3

Dimensions in millimeters (inches)

Keep-Out 3.5 mm x 3.5 mm for non terminating traces



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